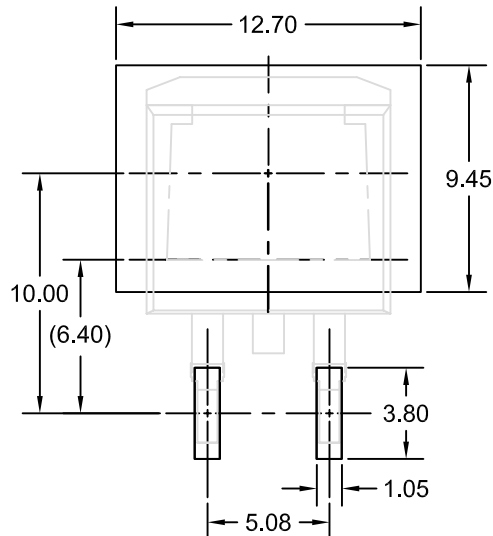
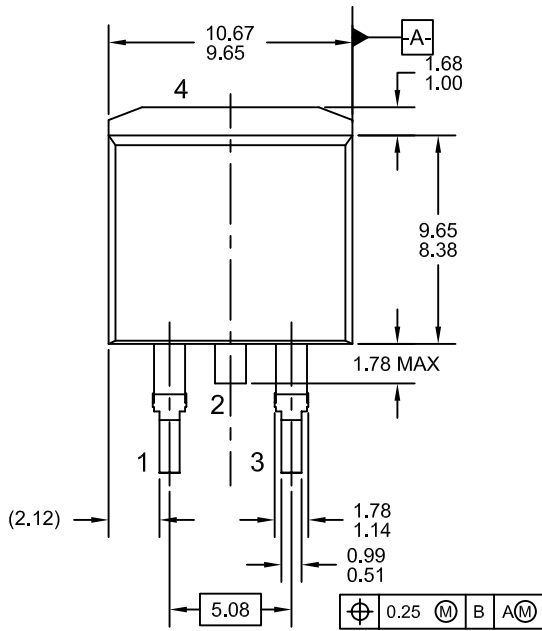
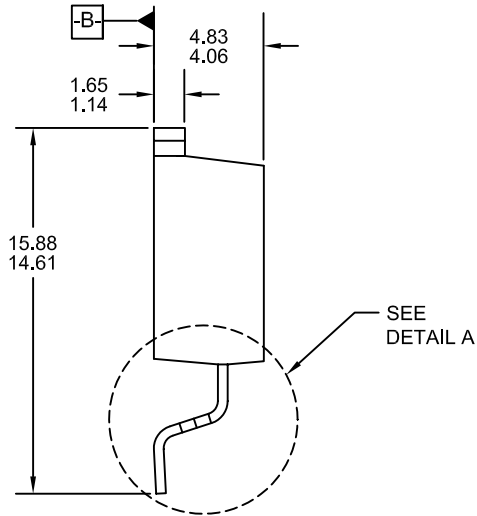
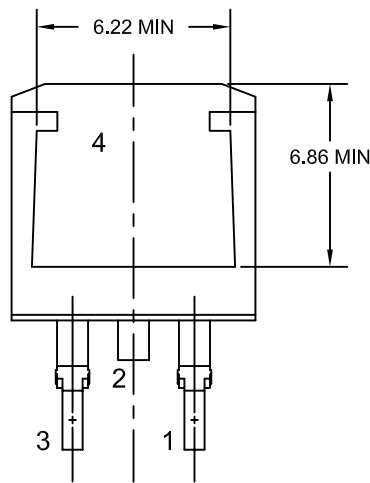


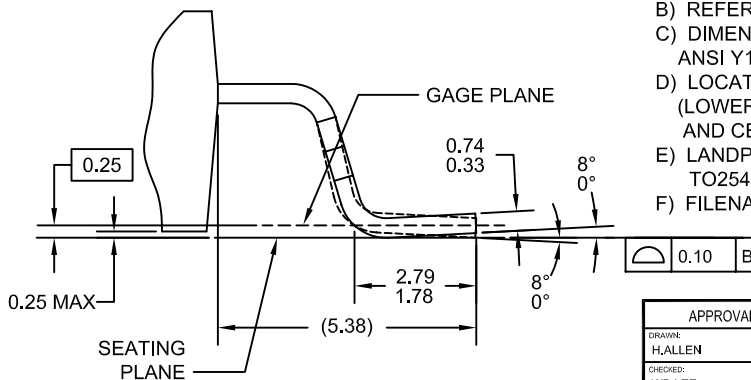
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
A	RELEASE TO DOCUMENT CONTROL	CB/085/99	08NOV1999	MRG
B	CHG HEATSNK DIM FR 1.25 TO 1.50; INQ DIM FR 1.25 TO 1.50; LD OUT FR 1.25 TO 1.50; ADD DIM 1.25; CHG THK FR 1.25 TO 1.50; NOT LSH FR 1.25 TO 1.50; ADD DETAIL A; CHG LD THCK FR 1.25 TO 1.50; CHG FOOT LSH FR 1.25 TO 1.50; ADD DIM 1.50; CHG LAND PATTERN DIM FR 6.20 TO 6.30 MIN; FR FOOT TO 5.00 MIN; FR ADD TO 4.00 MIN; FR 1.25 TO 1.50 MIN; DEL NOTE C; AND ARRANGE, ADD NOTE D.	CB/044/00	28FEB2000	MRG
C	CHG ORDERED FR 1.25 TO 1.50 MAX; LD THK FR 1.25 TO 1.50; INQ THCK FR 1.25 TO 1.50; HEAT SNK THCK FR 1.25 TO 1.50; LD THCK FR 1.25 TO 1.50; FOOT LANDING FR 1.25 TO 1.50; FOOT ANGLE FR 3 TO 5 DEG; PROFILE DIM FR 6.15 MAX TO 6.30 MAX; CHG HEAT SNK WID FR 6.20 TO 6.32 MIN; LEN FR 1.20 TO 1.80 MIN; REMOVE EJECTOR PIN MARK; ADD NOTE E.	CB/254/04	7OCT2004	RCM
D	REMOVE NOTE B; ADD NOTE E	CB/043/05	30MAR2005	MRG
5	REMOVED SITE INFO AND ECN COLUMN. ADDED NOTE F. TITLE CHANGED	06AUG2007		H.ALLEN
6	UPDATED HEATSNK PER IPC STANDARD. NOTE E IPC REFERENCE. FONT TO ARIAL. UPDATED DRAWING TITLE TO REFLECT JEDEC STANDARD.		02 MAY 09	H.ALLEN



LAND PATTERN RECOMMENDATION
UNLESS NOTED, ALL DIMS TYPICAL



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) ALL DIMENSIONS ARE IN MILLIMETERS.
 - B) REFERENCE JEDEC, TO-263, VARIATION AB.
 - C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.
 - D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).
 - E) LANDPATTERN RECOMMENDATION PER IPC TO254P1524X482-3N
 - F) FILENAME: TO263A02REV6



DETAIL A, ROTATED 90°
SCALE: 2X

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™		
DRAWN:	H.ALLEN	2 MAY 09	2LD, JEDEC TO-263, VARIATION AB, SURFACE MOUNT		
CHECKED:	WB LEE	2 MAY 09			
APPROVED:					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
INCH (MM)		1:1	NA	MKT-TO263A02	6
		FORMERLY: N/A			SHEET: 1 OF 1